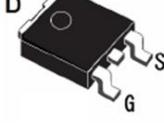
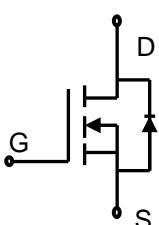


## Lonten N-channel 40V, 80A, 7.5mΩ Power MOSFET

Description	Product Summary
<p>These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.</p>	<p><math>V_{DSS}</math> 40V  <math>R_{DS(on).max} @ V_{GS}=10V</math> 7.5mΩ  <math>I_D</math> 80A</p>
Features	Pin Configuration
<ul style="list-style-type: none"> <li>◆ 40V,80A,<math>R_{DS(ON).max}=7.5m\Omega @ V_{GS}=10V</math></li> <li>◆ Improved dv/dt capability</li> <li>◆ Fast switching</li> <li>◆ 100% EAS Guaranteed</li> <li>◆ Green device available</li> </ul>	   <p>TO-251      TO-252</p>
Applications	N-Channel MOSFET
<ul style="list-style-type: none"> <li>◆ Motor Drives</li> <li>◆ UPS</li> <li>◆ DC-DC Converter</li> </ul>	

### Absolute Maximum Ratings $T_C = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	40	V
Continuous drain current ( $T_C = 25^\circ C$ )	$I_D$	80	A
Continuous drain current ( $T_C = 100^\circ C$ )		52	A
Pulsed drain current <sup>1)</sup>	$I_{DM}$	320	A
Gate-Source voltage	$V_{GSS}$	$\pm 20$	V
Avalanche energy <sup>2)</sup>	$E_{AS}$	144	mJ
Power Dissipation ( $T_C = 25^\circ C$ )	$P_D$	83	W
Storage Temperature Range	$T_{STG}$	-55 to +150	°C
Operating Junction Temperature Range	$T_J$	-55 to +150	°C

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.5	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	76	°C/W

**Package Marking and Ordering Information**

Device	Device Package	Marking
LNH04R075	TO-251	LNH04R075
LNG04R075	TO-252	LNG04R075

**Electrical Characteristics**
 $T_J = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static characteristics</b>						
Drain-source breakdown voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0 \text{ V}, I_{\text{D}}=250 \mu\text{A}$	40	---	---	V
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250 \mu\text{A}$	1.0	---	2.0	V
Drain-source leakage current	$I_{\text{DSS}}$	$V_{\text{DS}}=40 \text{ V}, V_{\text{GS}}=0 \text{ V}, T_J = 25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=32 \text{ V}, V_{\text{GS}}=0 \text{ V}, T_J = 125^\circ\text{C}$	---	---	10	$\mu\text{A}$
Gate leakage current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}}=20 \text{ V}, V_{\text{DS}}=0 \text{ V}$	---	---	100	nA
Gate leakage current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}}=-20 \text{ V}, V_{\text{DS}}=0 \text{ V}$	---	---	-100	nA
Drain-source on-state resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10 \text{ V}, I_{\text{D}}=20 \text{ A}$	---	5.6	7.5	$\text{m}\Omega$
		$V_{\text{GS}}=4.5 \text{ V}, I_{\text{D}}=10 \text{ A}$	---	7.1	9.5	$\text{m}\Omega$
Forward transconductance	$g_{\text{fs}}$	$V_{\text{DS}} = 5 \text{ V}, I_{\text{D}}=20 \text{ A}$	---	63	---	S
<b>Dynamic characteristics</b>						
Input capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 20 \text{ V}, V_{\text{GS}} = 0 \text{ V}, F = 1\text{MHz}$	---	2370	---	pF
Output capacitance	$C_{\text{oss}}$		---	316	---	
Reverse transfer capacitance	$C_{\text{rss}}$		---	212	---	
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 32 \text{ V}, V_{\text{GS}}=10 \text{ V}, I_{\text{D}} = 20 \text{ A}$	---	6.6	---	ns
Rise time	$t_r$		---	110.6	---	
Turn-off delay time	$t_{\text{d}(\text{off})}$		---	285.4	---	
Fall time	$t_f$		---	121.1	---	
Gate resistance	$R_g$	$V_{\text{GS}}=0 \text{ V}, V_{\text{DS}}=0 \text{ V}, F=1\text{MHz}$	---	1.7	---	$\Omega$
<b>Gate charge characteristics</b>						
Gate to source charge	$Q_{\text{gs}}$	$V_{\text{DS}}=32 \text{ V}, I_{\text{D}}=20 \text{ A}, V_{\text{GS}}=10 \text{ V}$	---	9.2	---	nC
Gate to drain charge	$Q_{\text{gd}}$		---	9.6	---	
Gate charge total	$Q_g$		---	51.2	---	
<b>Drain-Source diode characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_s$		---	---	80	A
Pulsed Source Current <sup>3)</sup>	$I_{\text{SM}}$		---	---	320	A
Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0 \text{ V}, I_s=20 \text{ A}, T_J=25^\circ\text{C}$	---	---	1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$I_s=20 \text{ A}, \text{di}/\text{dt}=100 \text{ A/us}, T_J=25^\circ\text{C}$	---	22.4	---	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		---	10.5	---	nC

Notes:

1: Repetitive Rating: Pulse width limited by maximum junction temperature.

2:  $V_{\text{DD}}=20 \text{ V}, V_{\text{GS}}=10 \text{ V}, L=0.5 \text{ mH}, I_{\text{AS}}=24 \text{ A}, R_g=25 \Omega$ , Starting  $T_J=25^\circ\text{C}$ .

3: Pulse Test: Pulse Width  $\leq 300 \mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

## Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

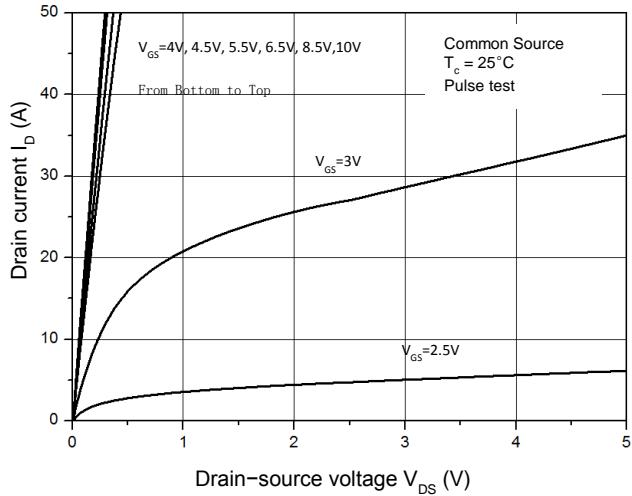


Figure 2. Transfer Characteristics

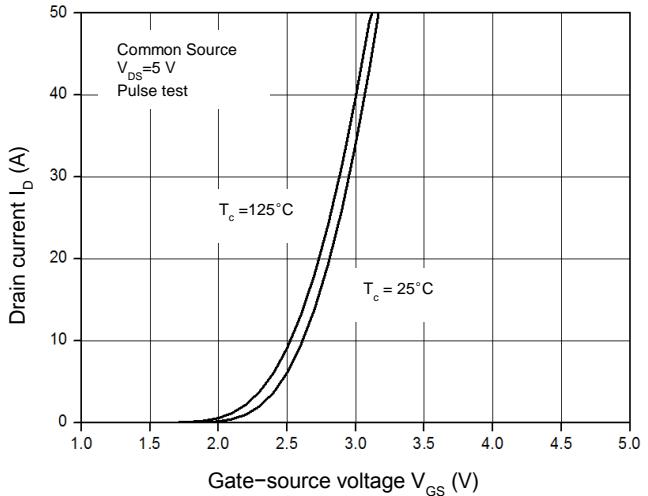


Figure 3. Capacitance Characteristics

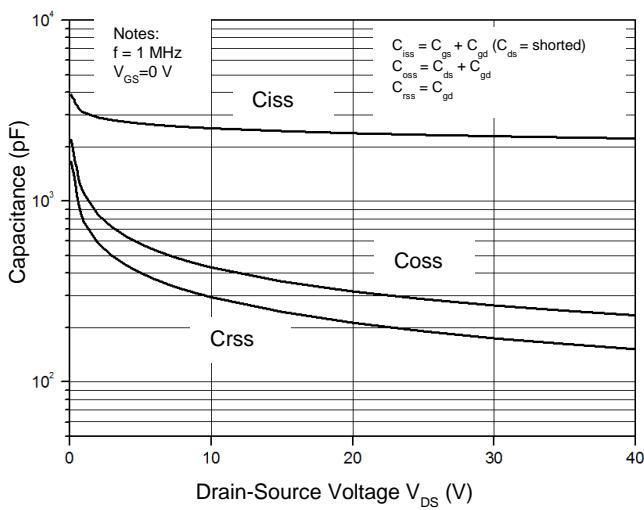


Figure 4. Gate Charge Waveform

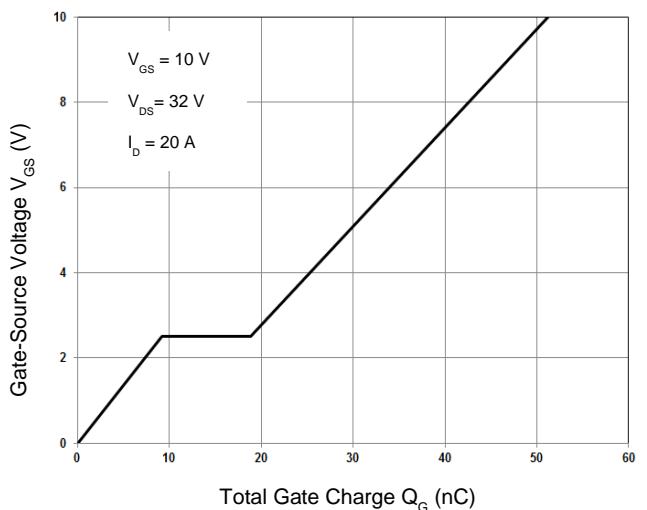


Figure 5. Body-Diode Characteristics

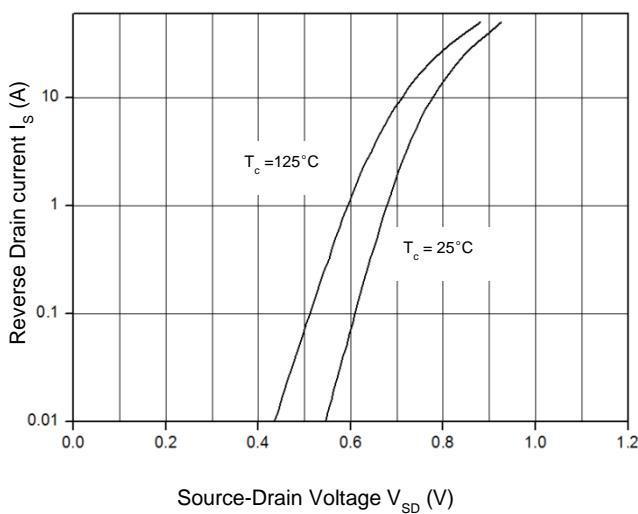


Figure 6. Rdson-Drain Current

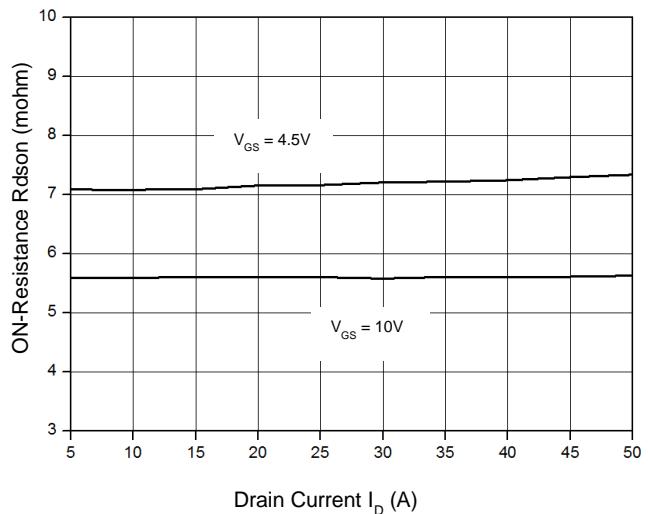


Figure 7. Rdson-Junction Temperature(°C)

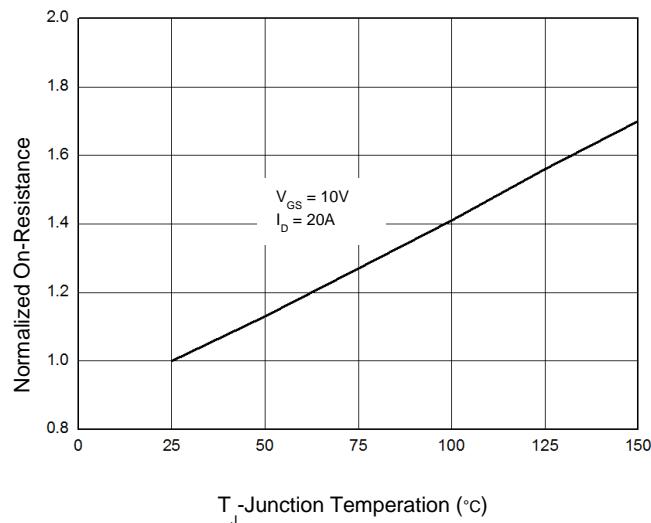


Figure 8. Maximum Safe Operating Area

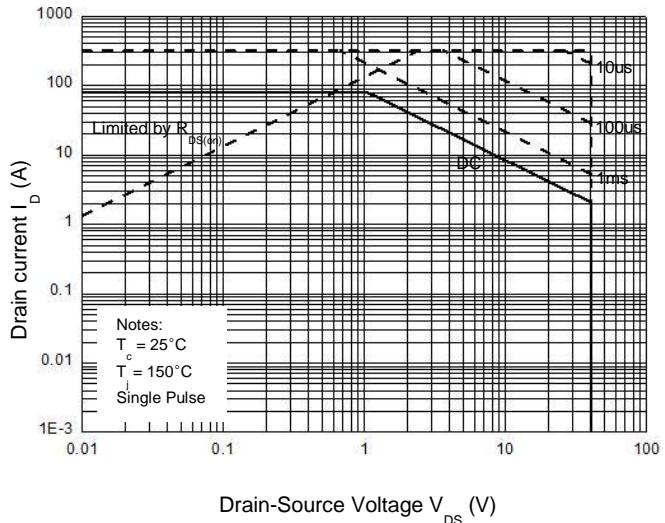
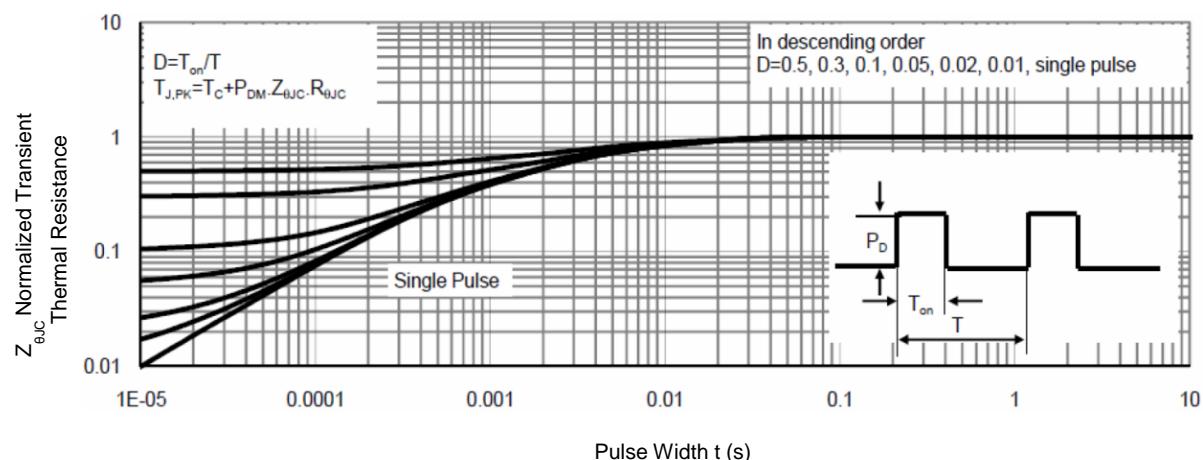


Figure 9. Normalized Maximum Transient Thermal Impedance (RthJC)



### Test Circuit & Waveform

Figure 8. Gate Charge Test Circuit & Waveform

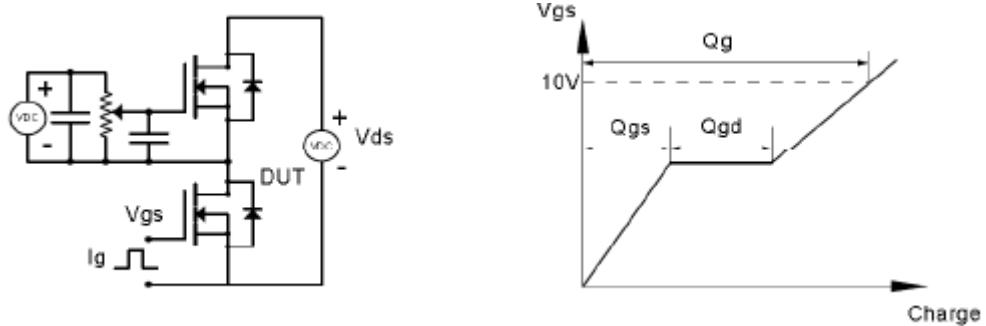


Figure 9. Resistive Switching Test Circuit & Waveforms

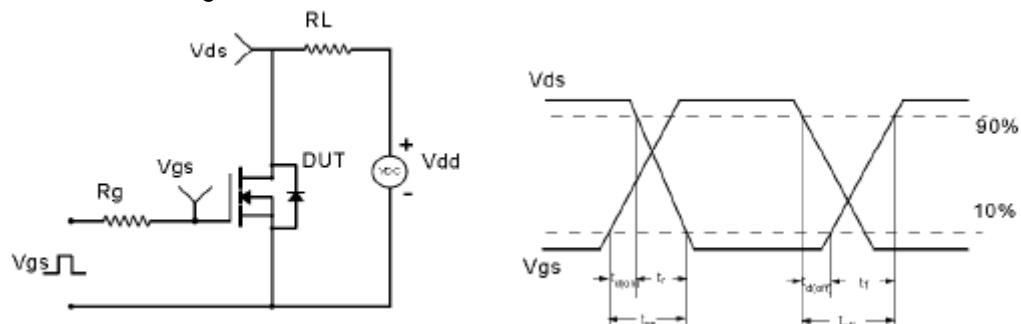


Figure 10. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

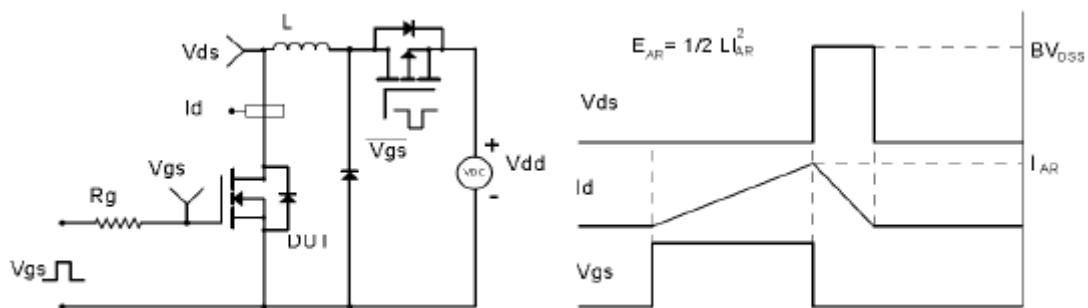
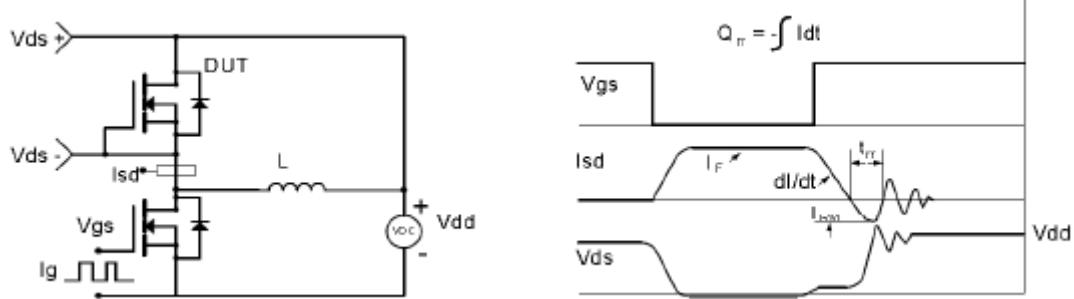
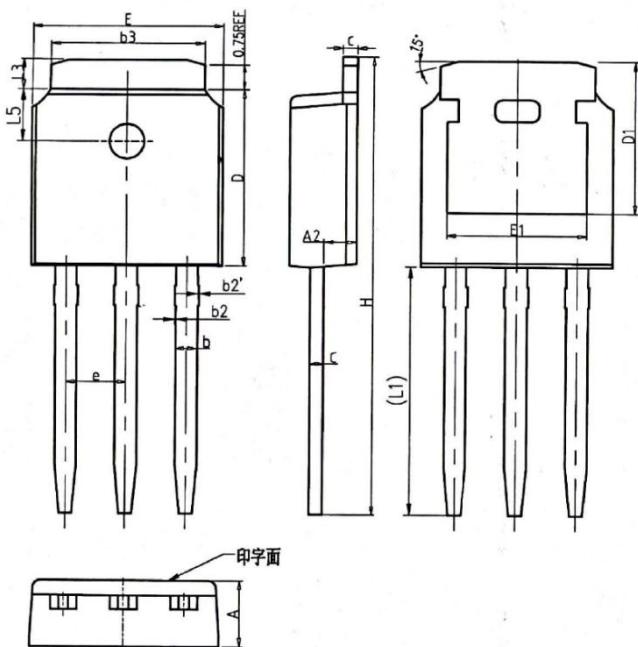


Figure 11. Diode Recovery Circuit & Waveform

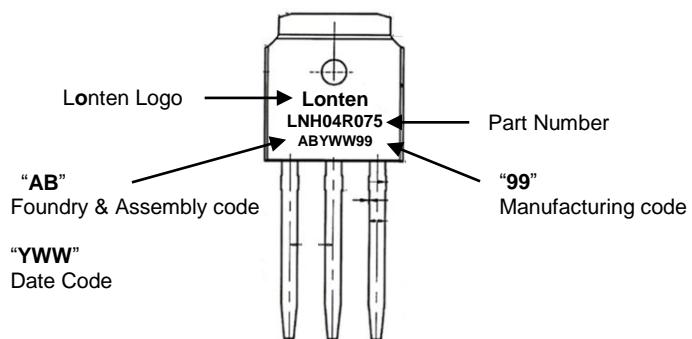


## Mechanical Dimensions for TO-251

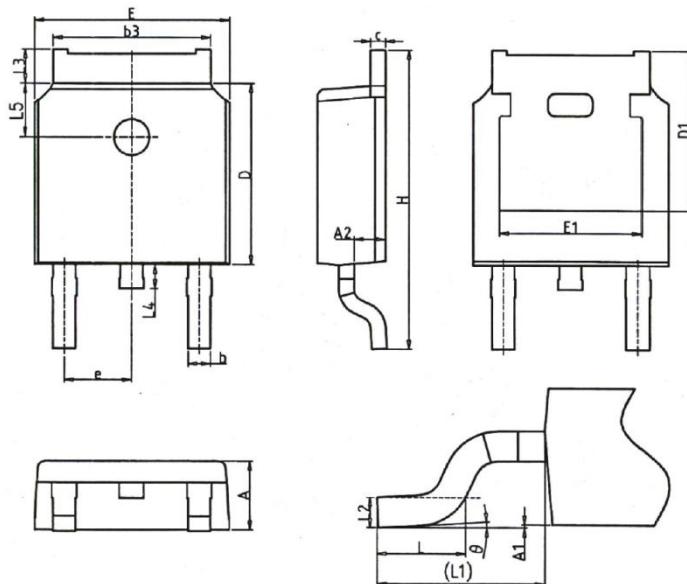


SYMBOL	COMMON DIMENSIONS			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	2.20	2.30	2.38	0.087	0.091	0.094
A2	0.97	1.07	1.17	0.038	0.042	0.046
b	0.68	0.78	0.90	0.027	0.031	0.035
b2	0.00	0.04	0.10	0.000	0.002	0.004
b2'	0.00	0.04	0.10	0.000	0.002	0.004
b3	5.20	5.33	5.46	0.205	0.210	0.215
c	0.43	0.53	0.61	0.017	0.021	0.024
D	5.98	6.10	6.22	0.235	0.240	0.245
D1	5.30REF			0.209REF		
E	6.40	6.60	6.73	0.252	0.260	0.265
E1	4.63	-	-	0.182	-	-
e	2.286BSC			0.090BSC		
H	16.22	16.52	16.82	0.639	0.650	0.662
L1	9.15	9.40	9.65	0.360	0.370	0.380
L3	0.88	1.02	1.28	0.035	0.040	0.050
L5	1.65	1.80	1.95	0.065	0.071	0.077

## TO-251 Part Marking Information

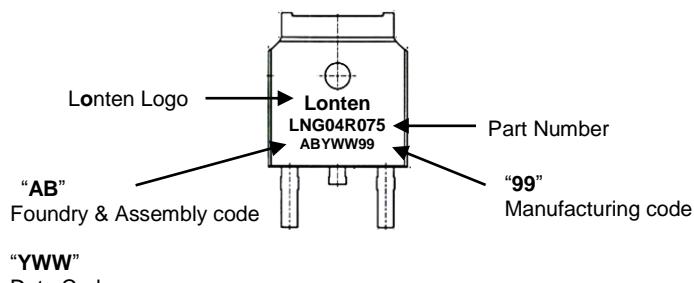


## Mechanical Dimensions for TO-252



SYMBOL	COMMON DIMENSIONS					
	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	2.20	2.30	2.38	0.087	0.091	0.094
A1	0.00	-	0.20	0.000	-	0.008
A2	0.97	1.07	1.17	0.038	0.042	0.046
b	0.68	0.78	0.90	0.027	0.031	0.035
b3	5.20	5.33	5.46	0.205	0.210	0.215
c	0.43	0.53	0.61	0.017	0.021	0.024
D	5.98	6.10	6.22	0.235	0.240	0.245
D1	5.30REF			0.209REF		
E	6.40	6.60	6.73	0.252	0.260	0.265
E1	4.63	-	-	0.182	-	-
e	2.286BSC			0.090BSC		
H	9.40	10.10	10.50	0.370	0.398	0.413
L	1.38	1.50	1.75	0.054	0.059	0.069
L1	2.90REF			0.114REF		
L2	0.51BSC			0.020BSC		
L3	0.88	-	1.28	0.035	-	0.050
L4	0.50	-	1.00	0.020	-	0.039
L5	1.65	1.80	1.95	0.065	0.071	0.077
$\theta$	0°	-	8°	0°	-	8°

## TO-252 Part Marking Information



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